


**3.00mm (.118") Pitch  
Micro-Fit 3.0, CPI™  
Micro-Fit 3.0, BMI™ CPI  
Vertical Headers**
**Micro-Fit 3.0 Family Offers Press-Fit Headers For High-Density Power and Signal Applications**

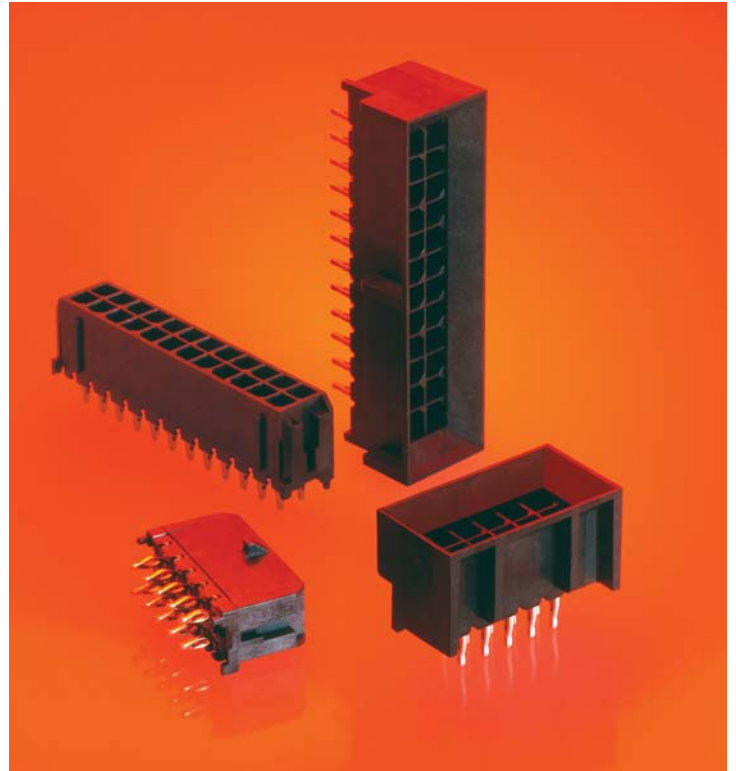
The Micro-Fit 3.0, CPI (Compliant Pin Interface) and Micro-Fit 3.0, BMI CPI (Blind-Mate version with Compliant Pin Interface) are vertical header product extensions featuring press-fit PC tails. These headers are designed for high-density applications where press-fit terminations are required. The CPI products are appropriate for both power and signal uses as they can carry up to 5.0A of current per circuit.

The standard Micro-Fit 3.0, CPI headers incorporate a compact housing that mates with standard wire-mount housings and crimp terminals for wire-to-board applications.

The Micro-Fit 3.0, BMI CPI headers feature a funnel entry to guide the mating receptacle into place. Micro-Fit 3.0, BMI headers mate exclusively with BMI components, which include panel-mount receptacles with crimp terminals and PCB receptacles for wire-to-board and board-to-board applications.

**Features and Benefits**

- CPI style (press-fit) pins require no soldering to the PCB
- Designed for multiple board thicknesses of 2.36mm (.093") or greater
- Dual-row vertical headers available in 2-24 circuits for the standard version and 4-24 circuits for the BMI (blind-mate) version
- Rated up to 5.0A of current for both power and signal applications in wire-to-board and board-to-board configurations
- Fully polarized with positive locks for proper mating
- Fully isolated contacts for electrical and mechanical integrity


**Reference Information**

Packaging: Tray  
UL File No.: E29179  
CSA File No.: LR19980  
TUV No.: R95107  
Designed In: Millimeters

**Electrical**

Voltage: 250V  
Current: 5.0A  
Contact Resistance: 10 milliohms max.  
Dielectric Withstanding Voltage: 1500 VAC  
Insulation Resistance: 1000 Megohms min.

**Mechanical**

Insertion Force to PCB: 35.6N (8.0lb) per circuit max.  
Retention Force to PCB: 106.8N (24.0lb) per circuit min.  
Mating Force: 8.0N (1.8lb) per circuit max.  
Unmating Force: 3.6N (0.8lb) per circuit min.  
Durability: 30 cycles

**Physical**

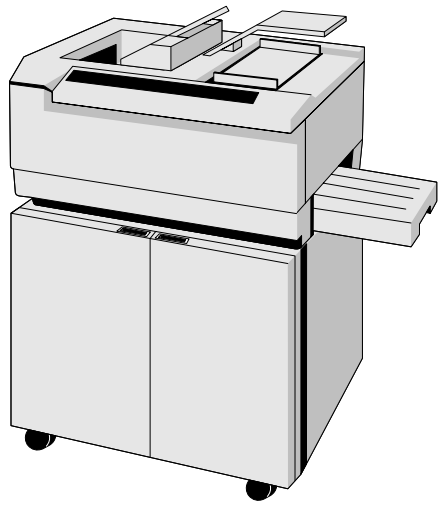
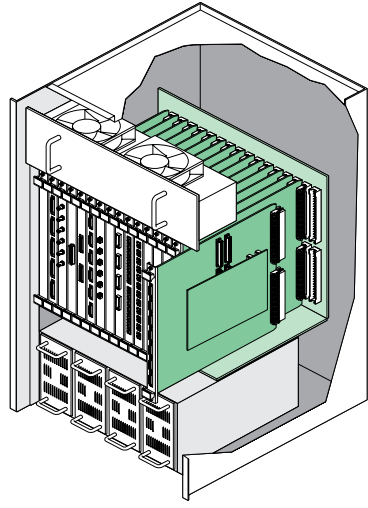
Housing: High-temperature polymer, UL 94V-0  
Contact: Brass alloy  
Plating:  
Contact area – 5.1µm (200µ") min. Tin, 0.38µm (15µ") min. select Gold or 0.76µm (30µ") min. select Gold  
PC tails – Tin/Lead  
Underplating: Nickel  
PCB Thickness: 2.36mm (.093") min.  
Operating Temperature: -40 to +105° C



# 3.00mm (.118") Pitch Micro-Fit 3.0, CPI™ Micro-Fit 3.0, BMI™ CPI Vertical Headers

## Applications

- Servers
- Workstations
- Personal Computers
- Mainframe Computers
- Notebook PCs
- Fan Tray Assemblies
- Power Supplies
- Office Equipment
- Vending and Gaming Machines



## ORDERING INFORMATION

Header Style	Circuit Size	Contact Plating		
		5.1µm (200µ") min. Tin	0.38µm (15µ") min. Gold	0.76µm (30µ") min. Gold
Micro-Fit 3.0, CPI	2	44914-0201	44914-0202	44914-0203
	4	44914-0401	44914-0402	44914-0403
	6	44914-0601	44914-0602	44914-0603
	8	44914-0801	44914-0802	44914-0803
	10	44914-1001	44914-1002	44914-1003
	12	44914-1201	44914-1202	44914-1203
	14	44914-1401	44914-1402	44914-1403
	16	44914-1601	44914-1602	44914-1603
	18	44914-1801	44914-1802	44914-1803
	20	44914-2001	44914-2002	44914-2003
	22	44914-2201	44914-2202	44914-2203
	24	44914-2401	44914-2402	44914-2403
Micro-Fit 3.0, BMI CPI	4	45280-0401	45280-0402	45280-0403
	6	45280-0601	45280-0602	45280-0603
	8	45280-0801	45280-0802	45280-0803
	10	45280-1001	45280-1002	45280-1003
	12	45280-1201	45280-1202	45280-1203
	14	45280-1401	45280-1402	45280-1403
	16	45280-1601	45280-1602	45280-1603
	18	45280-1801	45280-1802	45280-1803
	20	45280-2001	45280-2002	45280-2003
	22	45280-2201	45280-2202	45280-2203
	24	45280-2401	45280-2402	45280-2403

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